12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20260518000.1
Add Cu as Alternative Wire Base Metal for Selected Device(s)
Change Notification / Sample Request

Date: May 18, 2026
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20260518000.1
Change Notification / Sample Request
Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records**,** you have recently purchased these devices**.** The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
BQ29706DSER	BQ29706DSER
BQ29737DSER	NULL
SN65HVD62RGTR	SN65HVD62RGTR
BQ29740DSER	NULL
BQ29700DSER	BQ29700DSER
BQ29702DSER	BQ29702DSER
BQ29707DSER	BQ29707DSER
TPS40304DRCR	TPS40304DRCR
TPS40305DRCR	TPS40305DRCR
TPS43060RTER	TPS43060RTER
BQ29701DSER	BQ29701DSER
TPS43061RTER	TPS43061RTER
TPS43060RTET	TPS43060RTET
TPS43061RTET	TPS43061RTET
BQ29701DSET	BQ29701DSET
BQ29729DSER	BQ29729DSER
SN65HVD63RGTT	SN65HVD63RGTT
BQ29705DSER	BQ29705DSER
BQ29733DSET	BQ29733DSET
TPS40345DRCT	NULL
BQ29700DSET	BQ29700DSET

Technical details of this Product Change follow on the next page(s).

PCN Number:	20260518000.1	PCN Date:	May 18, 2026
Title:	Add Cu as Alternative Wire Base Metal for Selected Device(s)		
Customer Contact:	Change Management team	Dept:	Quality Services
Proposed 1st Ship Date:	August 16, 2026	Estimated Sample Availability:	July 17, 2026

***Sample requests received after** July 17, 2026 **will not be supported.**

Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Material
☒	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process
☒	Assembly Materials	☐	Part number change	☐	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Material
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of new assembly material set to add Cu as an additional bond wire option for devices listed in "Product affected" section below. Devices will remain in current assembly facility and piece part changes as follows:

Group 1

Material	Current	Proposed
Wire diam/type	0.8mil Au	0.8mil Cu

Group 2

Material	Current	Proposed
Wire diam/type	0.96mil Au	0.96mil Cu

Reason for Change:

Continuity of supply.

1) To align with world technology trends and use wiring with enhanced mechanical and electrical properties
2) Maximize flexibility within our Assembly/Test production sites.
3) Cu is easier to obtain and stock

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

Review the SDP for full evaluation of the change based on the customer use case.

Impact on Environmental Ratings:

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

None

Group 1 Product Affected:

BQ29700DSER	BQ29707DSER	BQ29723DSET
BQ29700DSER	BQ29707DSER	BQ29728DSER
BQ29700DSET	BQ29707DSET	BQ29728DSET
BQ29700DSET	BQ29707DSET	BQ29729DSER
BQ29700DSETG4	BQ29707DSETG4	BQ29729DSER

BQ29701DSER	BQ29716DSER	BQ29729DSET
BQ29701DSER	BQ29716DSET	BQ29729DSET
BQ29701DSET	BQ29717DSER	BQ29732DSER
BQ29701DSET	BQ29717DSER	BQ29732DSET
BQ29702DSER	BQ29717DSET	BQ29733DSER
BQ29702DSET	BQ29717DSET	BQ29733DSERG4
BQ29702DSETG4	BQ29718DSER	BQ29733DSET
BQ29703DSER	BQ29718DSER	BQ29736DSER
BQ29703DSET	BQ29718DSET	BQ29736DSET
BQ29704DSER	BQ29718DSET	BQ29737DSER
BQ29704DSET	BQ29719DSER	BQ29737DSET
BQ29705DSER	BQ29719DSET	BQ29739DSER
BQ29705DSET	BQ29723DSER	BQ29740DSER
BQ29706DSER	BQ29723DSER	
BQ29706DSET	BQ29723DSET	

Group 2 Product Affected:

SN1001021DRCR	TPS40303DRCR	TPS43060RTER
SN65HVD62RGT1R	TPS40303DRCT	TPS43060RTERG4
SN65HVD62RGTR	TPS40304DRCR	TPS43060RTET
SN65HVD62RGTRG4	TPS40304DRCT	TPS43061RTER
SN65HVD62RGTT	TPS40305DRCR	TPS43061RTERG4
SN65HVD63RGTR	TPS40305DRCT	TPS43061RTET
SN65HVD63RGTRG4	TPS40345DRCR	
SN65HVD63RGTT	TPS40345DRCT	

Group 1 Qualification Report

Approve Date 11-March-2024

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: BQ29700DSER	QBS Process Reference: SN3257QDYYRQ1	QBS Process, Product Reference: BQ29700DSER	QBS Package Reference: TPS3703C7500DSERQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	2/154/2[1]
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	2/154/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	2/154/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	2/154/0
HTOL	B1	Life Test	150C	300 Hours	-	3/231/0	-	-
ELFR	B2	Early Life Failure Rate	150C	24 Hours	-	3/2400/0	-	-
ESD	E2	ESD CDM	-	250 Volts	-	-	1/3/0	-
ESD	E2	ESD HBM	-	1000 Volts	-	-	1/3/0	-
LU	E4	Latch-Up	Per JESD78	-	-	-	1/3/0	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	-	-	1/30/0	-

QBS: Qual By Similarity
Qual Device BQ29700DSER is qualified at MSL2 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
Green/Pb-free Status:
Qualified Pb-Free(SMT) and Green
TI Qualification ID: R-NPD-2108-057
[1]-Missing/Lost Units

Group 1 Qualification Report

Approve Date 14-May-2026

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name	Condition	Duration	Qual Device: BQ29700DSER	QBS Package Reference: TMUX4051BQBRQ1
HAST	Biased HAST	130C/85%RH	96 Hours	-	3/231/0
UHAST	Unbiased HAST	130C/85%RH	96 Hours	-	3/231/0
TC	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0
HTSL	High Temperature Storage Life	150C	1000 Hours	-	1/45/0
CHAR	Electrical Characterization	Per Datasheet Parameters	-	3/90/0	-
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	(per mfg. Site specification)	Pass	Pass

QBS: Qual By Similarity, also known as Generic Data
Qual Device BQ29700DSER is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-CHG-2602-095

Group 2 Qualification Report

Approve Date 29-APRIL -2026

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name	Condition	Duration	Qual Device: SN65HVD63RGTR	Qual Device: TPS43061RTER
AC	Autoclave	121C/15psig	96 Hours	3/231/0	3/231/0
TC	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	3/231/0
HTSL	High Temperature Storage Life	170C	420 Hours	-	3/231/0
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	(per mfg. Site specification)	Pass	Pass

QBS: Qual By Similarity, also known as Generic Data
Qual Device SN65HVD63RGTR is qualified at MSL2 260C
Qual Device TPS43061RTER is qualified at MSL2 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-CHG-2602-074

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a ‘product qualification family’ for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled “QBS Process” (for wafer fab process), “QBS Package” (for assembly process) and “QBS Product” (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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